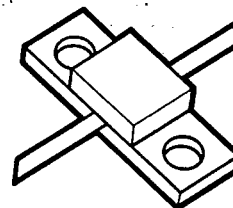


**MRA1014-2, MRA1014-6, MRA1014-12, MRA1014-35**

**MICROAMP® L-Band Class C Power Transistors**

- 2 to 35 Watts
- Broadband 1000-1400 MHz
- Internally Compensated\*
- Gold Metalized
- Diffused Ballast Resistors
- MTF Data
- Common Base



MRA .25

**Electrical Characteristics ( $T_{flange} = 25\text{ }^{\circ}\text{C}$ )**

Symbol	Characteristic	MRA1014-2	MRA1014-6	MRA1014-12	MRA1014-35A
$BV_{CES}$	Collector-Base Breakdown Voltage	$I_C = 20\text{ mA}$ 50 V Min	$I_C = 40\text{ mA}$ 50 V Min	$I_C = 80\text{ mA}$ 50 V Min	$I_C = 200\text{ mA}$ 50 V Min
$BV_{EBO}$	Emitter-Base Breakdown Voltage	$I_E = 0.25\text{ mA}$ 3.5 V Min	$I_E = 0.5\text{ mA}$ 3.5 V Min	$I_E = 1.0\text{ mA}$ 3.5 V Min	$I_E = 2.5\text{ mA}$ 3.5 V Min
$I_{CBO}$	Collector Cutoff Current $I_E = 0$	$V_{CB} = 28\text{ V}$ 0.5 mA	$V_{CB} = 28\text{ V}$ 1.0 mA	$V_{CB} = 28\text{ V}$ 2.0 mA	$V_{CB} = 28\text{ V}$ 5.0 mA
$I_C$	Max Continuous Collector Current $V_{CE} = 4\text{ V}$	0.5 A	1.0A	2.0A	5.0A
$h_{FE}$	Forward Current Transfer Ratio $V_{CE} = 5\text{ V}$	$I_C = 0.1\text{ A}$ 10-100	$I_C = 0.2\text{ A}$ 10-100	$I_C = 0.4\text{ A}$ 10-100	$I_C = 1.0\text{ A}$ 10-100
$\theta_{JF}$	Thermal Resistance Junction to Flange (at rated RF output)	15 $^{\circ}\text{C/W}$	8 $^{\circ}\text{C/W}$	4.5 $^{\circ}\text{C/W}$	2.5 $^{\circ}\text{C/W}$
$P_o$	Min Broadband Power Output	2.0 W	6.0 W	12.0 W	35.0 W
$C_{ob}$	Max Collector-Base Capacitance $V_{CB} = 28\text{ V}$ , $f = 1\text{ MHz}$	4.5 pF	8 pF	12 pF	Internal Shunt L
$P_{G(dB)}$	Min Power Gain in dB $V_{CB} = 28\text{ V}$	$P_o = 2.0\text{ W}$ 8.2 dB	$P_o = 6.0\text{ W}$ 7.4 dB	$P_o = 12.0\text{ W}$ 7.8 dB	$P_o = 35.0\text{ W}$ 7.0 dB
$\eta_c$	Min Broadband Collector Efficiency	$P_o = 2.0\text{ W}$ 45 %	$P_o = 6.0\text{ W}$ 50 %	$P_o = 12.0\text{ W}$ 50 %	$P_o = 35.0\text{ W}$ 50 %
$T_j$		-65 to +200 $^{\circ}\text{C}$			
$T_{STG}$		-65 to +150 $^{\circ}\text{C}$			

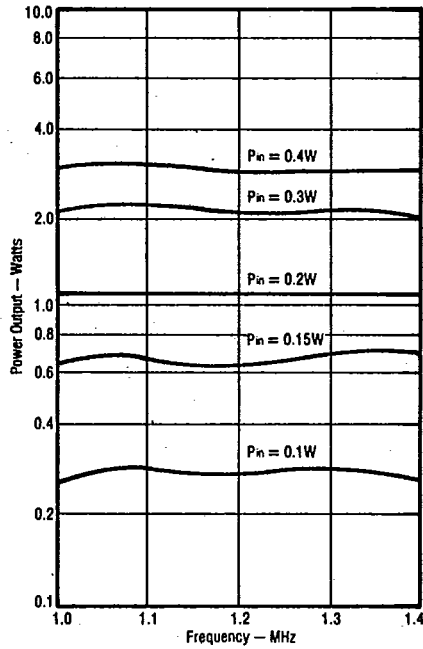
\*The concept of input and/or output matching using MOS capacitors, wire bonds and other techniques is patented by TRW, Inc. (US #3,713,006).

MRA 1014 Series

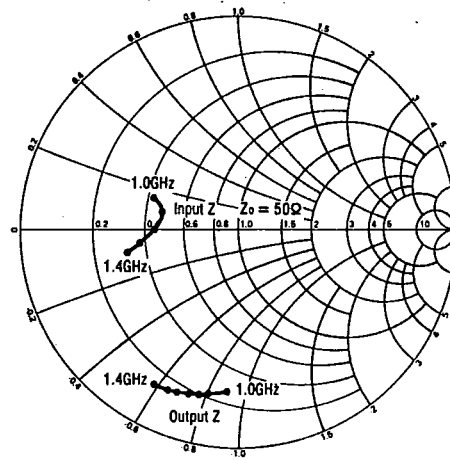
T-33-11

MRA1014-2 — 2 WATTS BROADBAND

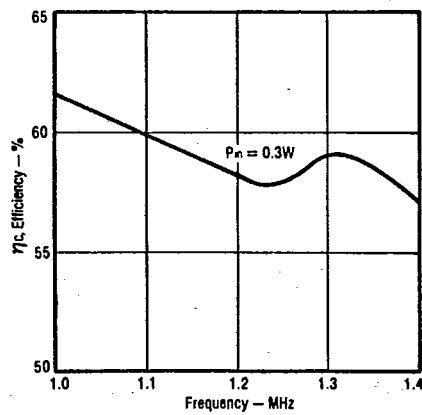
Typical Power Output vs Frequency



Impedance Data  
Vcc = 28V



Typical Efficiency vs Frequency

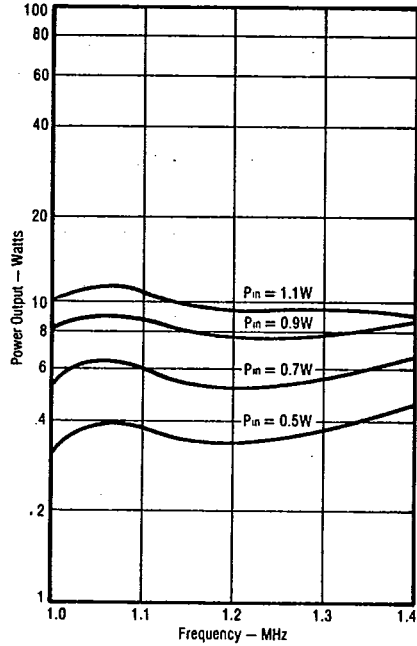


MRA 1014 Series

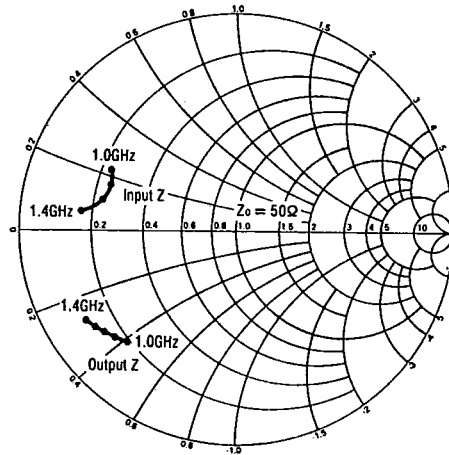
T-33-11

MRA1014-6 — 6 WATTS BROADBAND

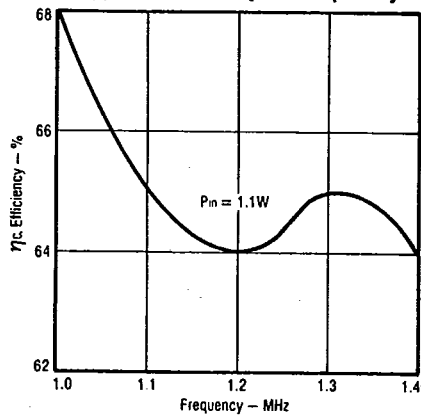
Typical Power Output vs Frequency



Impedance Data  
Vcc = 28V



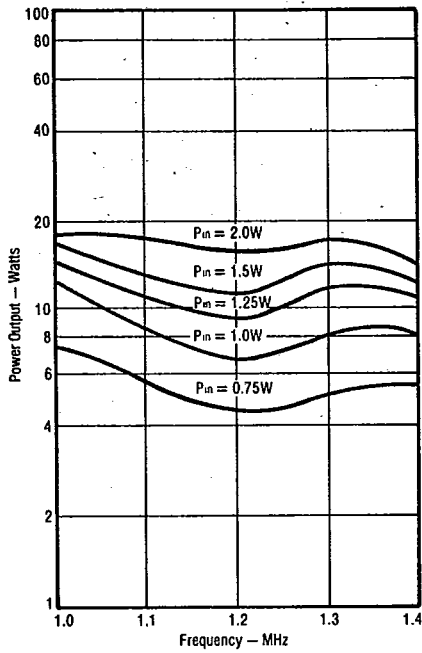
Typical Efficiency vs Frequency



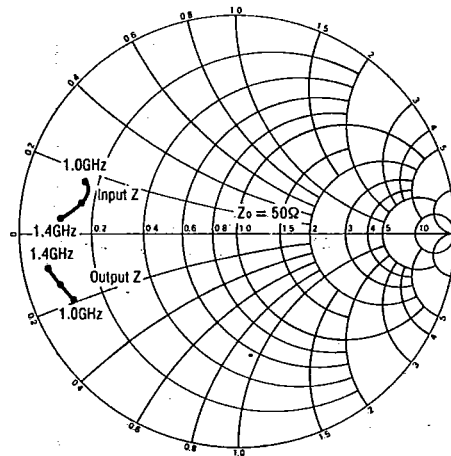
**MRA 1014 Series** **T-33-11**

**MRA1014-12 — 12 WATTS BROADBAND**

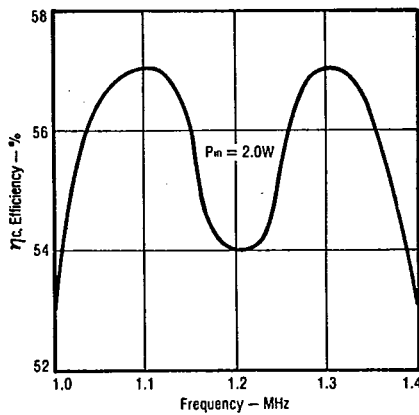
**Typical Power Output vs Frequency**



**Impedance Data**  
 $V_{cc} = 28V$



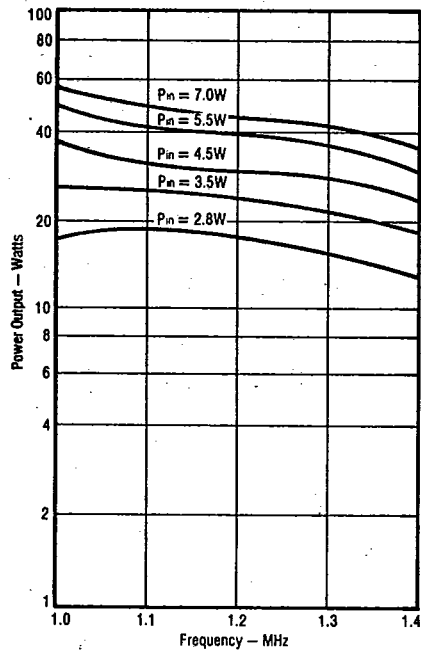
**Typical Efficiency vs Frequency**



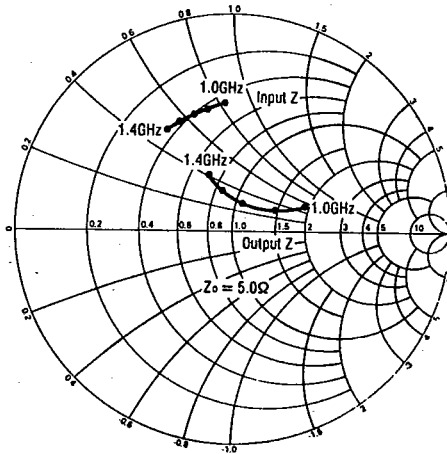
MRA 1014 Series T-33-11

MRA1014-35 — 35 WATTS BROADBAND

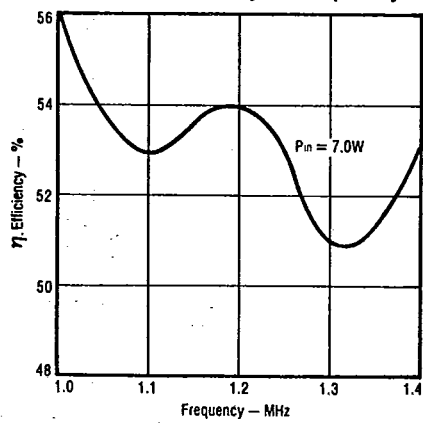
Typical Power Output vs Frequency



Impedance Data  
Vcc = 28V  
(5Ω Center)



Typical Efficiency vs Frequency

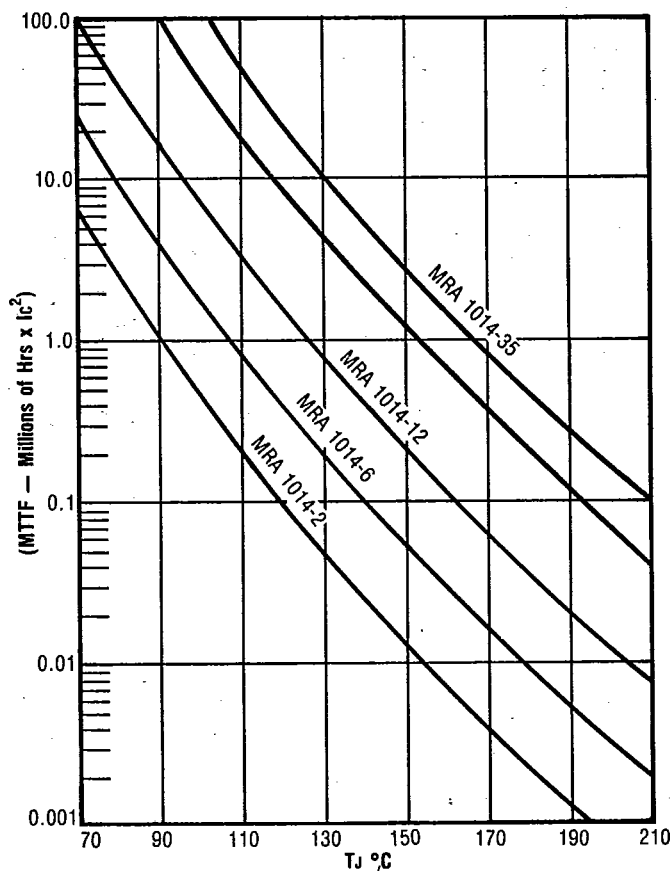


MRA 1014 Series

T-33-11

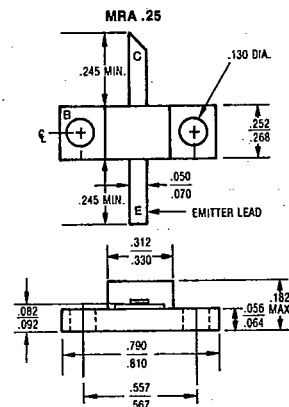
**MTTF FACTOR (Normalized to 1 Ampere<sup>2</sup> Continuous Duty)**

The graph shown below displays MTTF in hours x ampere<sup>2</sup> emitter current for each of the devices. Life tests at elevated temperatures have correlated to better than ±10% to the theoretical prediction for metal failure. Sample MTTF calculations based on operating conditions are included below.



**Example of MTTF for MRA1014-12 Conditions**

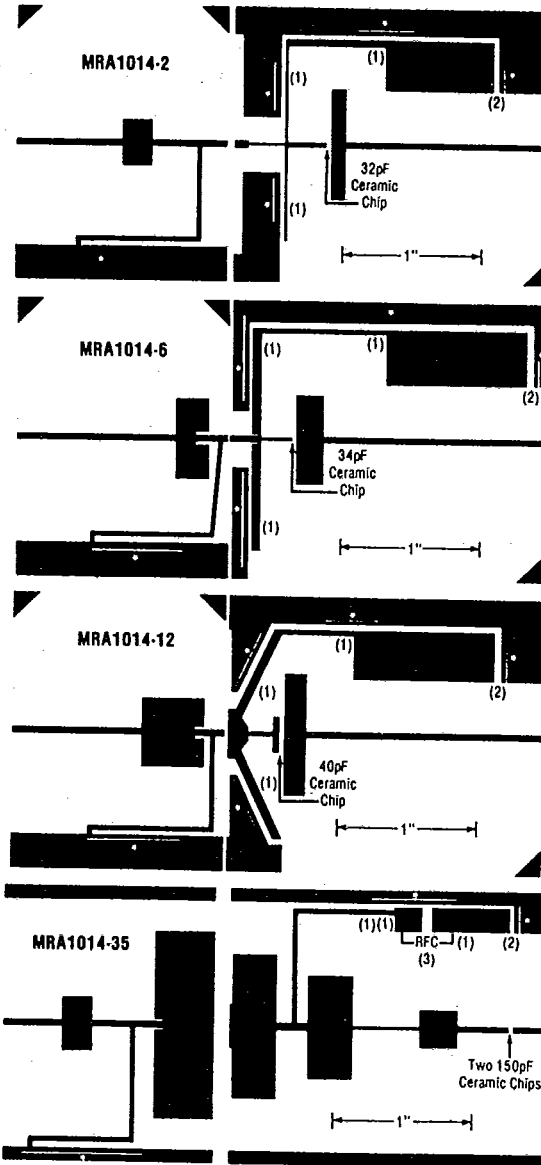
$P_o = 12W$   
 $P_{IN} = 2.0W$   
 $V_{CC} = 28V$   
 $\eta\% = 50$   
 $T_{FLANGE} = 70^\circ C$   
 $I_c \approx I_E = \frac{100 \times P_o}{\eta_c \times V_{CC}} = 0.857 A$   
 $P_{DISS} = P_{IN} + V_{CC} \cdot I_c - P_o = 13.99W$   
 $T_{JUNC} = T_{FLANGE} + \theta_{JF} \times P_{DISS} = 132.9^\circ C$   
 $MTTF = \frac{0.7 \times 10^6 \text{ Hrs Amp}^2}{I_c^2} = 953,095 \text{ Hrs}$   
 $MTTF = 108.8 \text{ Yrs}$



MRA1014 Series

TEST CIRCUIT BOARDS FOR MRA1014 SERIES

NOTE: Scale is not 1:1.



\*Foil wrap or plate around to ground plane. Board material 0.020 inch glass-telton  $\epsilon_r = 2.55$ .  
 (1) Bypass capacitor to ground (150pF chip).  
 (2) Use 8+ bypass of 0.01 and 1 $\mu$ F capacitors at this point.  
 (3) 10 turns #20 enamel close wound on 0.040 mandrel.